# RS1E320GN

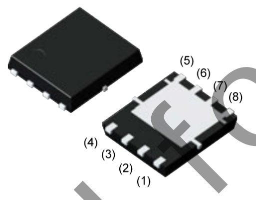
Nch 30V 80A Power MOSFET

Datasheet

| | |
|---|---|
| $V_{DSS}$ | 30V |
| $R_{DS(on)}$(Max.) | 1.9mΩ |
| $I_D$ | ±80A |
| $P_D$ | 34W |

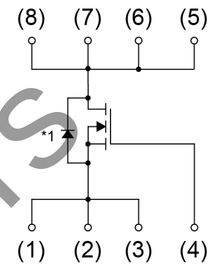
## ●Outline

HSOP8




## ●Inner circuit

(1) Source
(2) Source
(3) Source
(4) Gate
(5) Drain
(6) Drain
(7) Drain
(8) Drain
*1 Body Diode




## ●Features

1) Low on - resistance.
2) High power package (HSOP8).
3) Pb-free lead plating ; RoHS compliant
4) Halogen free
5) 100% Rg and UIS tested.

## ●Packaging specifications

| | | |
|---|---|---|
| Type | Packing | Embossed Tape |
| | Reel size (mm) | 330 |
| | Tape width (mm) | 12 |
| | Basic ordering unit (pcs) | 2500 |
| | Taping code | TB |
| | Marking | RS1E320GN |

## ●Application

Switching

## ●Absolute maximum ratings ($T_a$ = 25°C ,unless otherwise specified)

| Parameter | | Symbol | Value | Unit |
|---|---|---|---|---|
| Drain - Source voltage | | $V_{DSS}$ | 30 | V |
| Continuous drain current | $T_c$ = 25°C | $I_D$*1 | ±80 | A |
| | $T_a$ = 25°C | $I_D$ | ±32 | A |
| Pulsed drain current | | $I_{DP}$*2 | ±128 | A |
| Gate - Source voltage | | $V_{GSS}$ | ±20 | V |
| Avalanche current, single pulse | | $I_{AS}$*3 | 32 | A |
| Avalanche energy, single pulse | | $E_{AS}$*3 | 77 | mJ |
| Power dissipation | | $P_D$*1 | 34 | W |
| | | $P_D$*4 | 3.0 | W |
| Junction temperature | | $T_j$ | 150 | ℃ |
| Operating junction and storage temperature range | | $T_{stg}$ | -55 to +150 | ℃ |

## ●Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | |
| Thermal resistance, junction - case | $R_{thJC}$ *1 | - | - | 3.6 | °C/W |
| Thermal resistance, junction - ambient | $R_{thJA}$ *4 | - | - | 41.7 | °C/W |

## ●Electrical characteristics ($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min. | Typ. | Max. | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}$ = 0V, $I_D$ = 1mA | 30 | - | - | V |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$ | $I_D$ = 1mA referenced to 25°C | - | 28 | - | mV/°C |
| Zero gate voltage drain current | $I_{DSS}$ | $V_{DS}$ = 24V, $V_{GS}$ = 0V | - | - | 1 | μA |
| Gate - Source leakage current | $I_{GSS}$ | $V_{GS}$ = ±20V, $V_{DS}$ = 0V | - | - | ±100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$ , $I_D$ = 1mA | 1.2 | - | 2.5 | V |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$ | $I_D$ = 1mA referenced to 25°C | - | -3.87 | - | mV/°C |
| Static drain - source on - state resistance | $R_{DS(on)}$ *5 | $V_{GS}$ = 10V, $I_D$ = 32A | - | 1.4 | 1.9 | mΩ |
| | | $V_{GS}$ = 4.5V, $I_D$ = 32A | - | 1.8 | 2.9 | |
| Gate resistance | $R_G$ | f=1MHz, open drain | - | 1.4 | - | Ω |
| Forward Transfer Admittance | $\|Y_{fs}\|$ *5 | $V_{DS}$ = 5V, $I_D$ = 32A | 35.0 | - | - | S |

*1 Tc = 25°C, Limited only by maximum temperature allowed.

*2 Pw≦10μs , Duty cycle≦1%

*3 L ≈ 0.1mH, $V_{DD}$ = 15V, $R_G$ = 25Ω, STARTING $T_j$ = 25°C Fig.3-1,3-2

*4 Mounted on a Cu board (40×40×0.8mm)

*5 Pulsed

## ●Electrical characteristics ($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values Min. | Values Typ. | Values Max. | Unit |
|---|---|---|---|---|---|---|
| Input capacitance | $C_{iss}$ | $V_{GS}$ = 0V | - | 2850 | - | pF |
| Output capacitance | $C_{oss}$ | $V_{DS}$ = 15V | - | 740 | - | pF |
| Reverse transfer capacitance | $C_{rss}$ | f = 1MHz | - | 210 | - | pF |
| Turn - on delay time | $t_{d(on)}$ *5 | $V_{DD}$ ≃ 15V, $V_{GS}$ = 10V | - | 21.8 | - | ns |
| Rise time | $t_r$ *5 | $I_D$ = 16A | - | 15.6 | - | ns |
| Turn - off delay time | $t_{d(off)}$ *5 | $R_L$ ≃ 0.93Ω | - | 74.6 | - | ns |
| Fall time | $t_f$ *5 | $R_G$ = 10Ω | - | 28.5 | - | ns |

## ●Gate charge characteristics ($T_a$ = 25°C)

| Parameter | Symbol | Conditions | | Values Min. | Values Typ. | Values Max. | Unit |
|---|---|---|---|---|---|---|---|
| Total gate charge | $Q_g$ *5 | $V_{DD}$ ≃ 15V, $I_D$ = 32A | $V_{GS}$ = 10V | - | 42.8 | - | nC |
| | | | $V_{GS}$ = 4.5V | - | 19.6 | - | nC |
| Gate - Source charge | $Q_{gs}$ *5 | | $V_{GS}$ = 4.5V | - | 11.6 | - | nC |
| Gate - Drain charge | $Q_{gd}$ *5 | | $V_{GS}$ = 4.5V | - | 6.7 | - | nC |

## ●Body diode electrical characteristics (Source-Drain) ($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values Min. | Values Typ. | Values Max. | Unit |
|---|---|---|---|---|---|---|
| Continuous forward current | $I_S$ | $T_a$ = 25℃ | - | - | 2.5 | A |
| Pulse forward current | $I_{SP}$ *2 | $T_a$ = 25℃ | - | - | 128 | A |
| Forward voltage | $V_{SD}$ *5 | $V_{GS}$ = 0V, $I_S$ = 2.5A | - | - | 1.2 | V |
| Reverse recovery time | $t_{rr}$ *5 | $I_S$ = 32A, $V_{GS}$=0V, di/dt = 100A/μs | - | 37.8 | - | ns |
| Reverse recovery charge | $Q_{rr}$ *5 | $I_S$ = 32A, $V_{GS}$=0V, di/dt = 100A/μs | - | 35.2 | - | nC |

## ●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

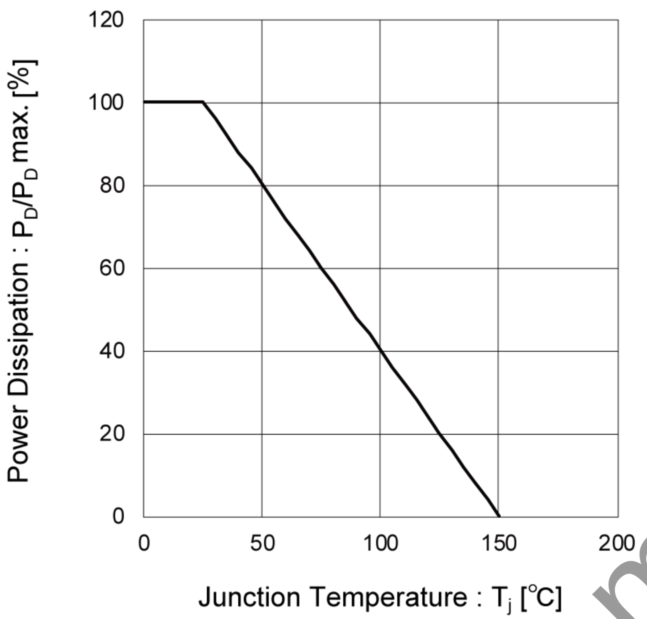



Fig.2 Maximum Safe Operating Area

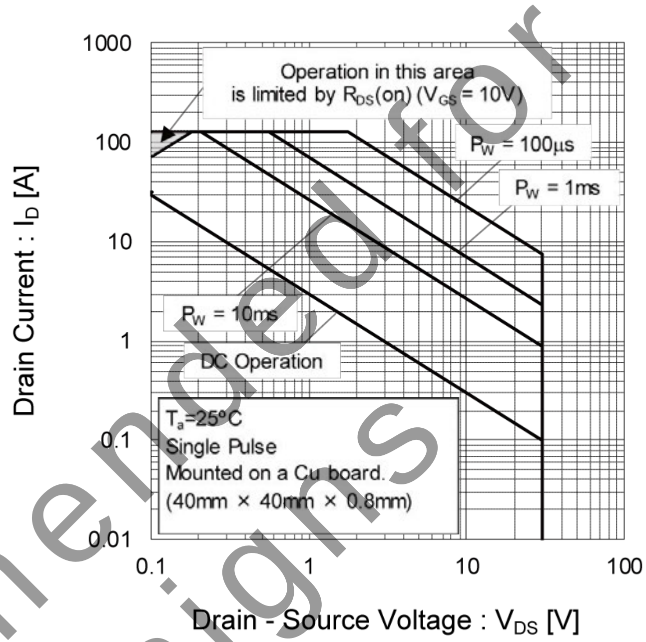



Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

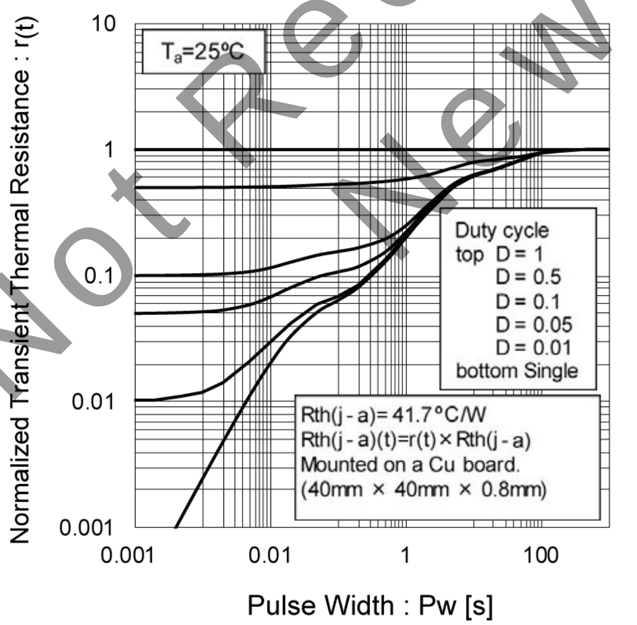
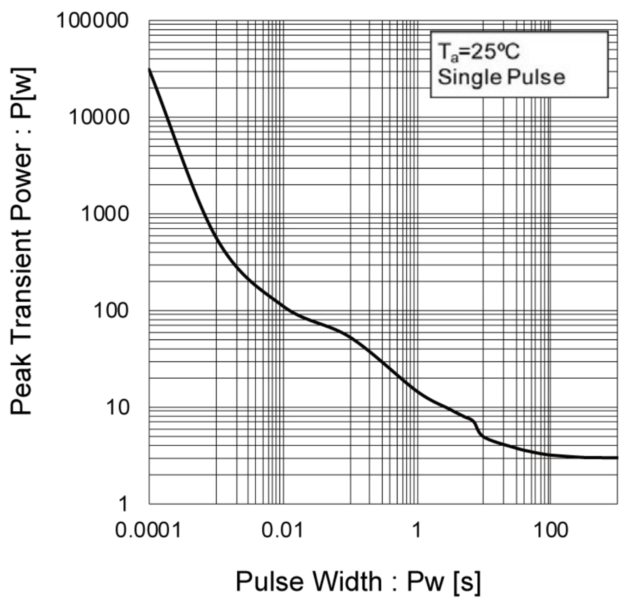



Fig.4 Single Pulse Maximum Power dissipation



## ●Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

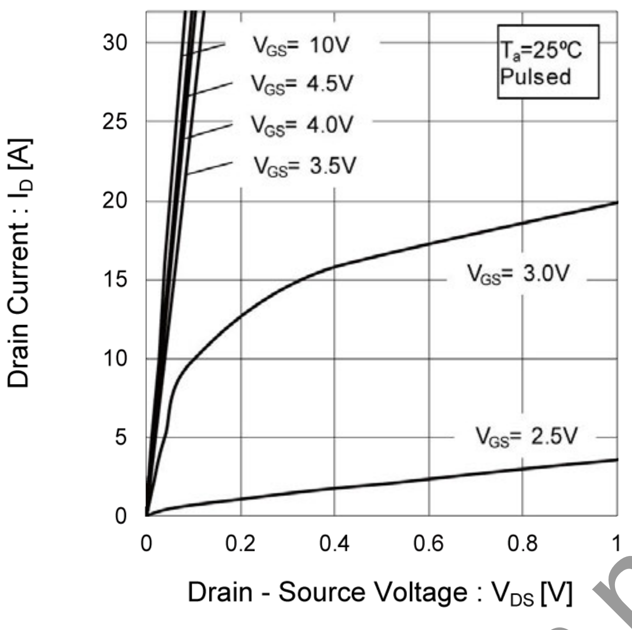



Fig.6 Typical Output Characteristics(II)

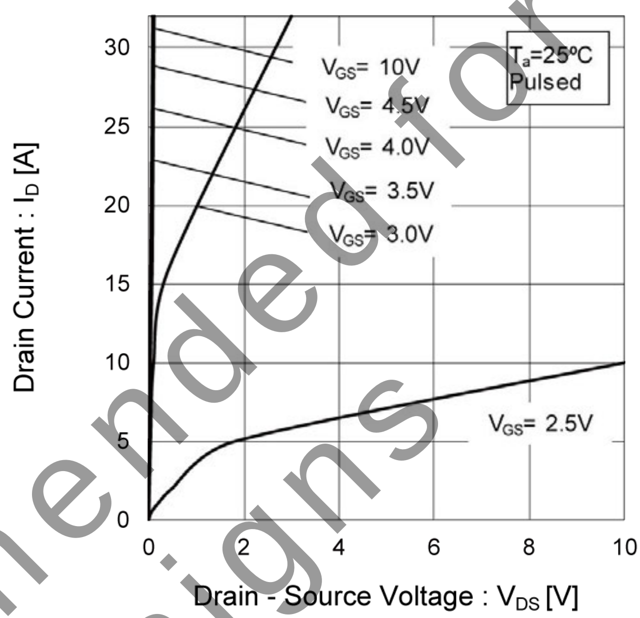



Fig.7 Breakdown Voltage vs.
Junction Temperature

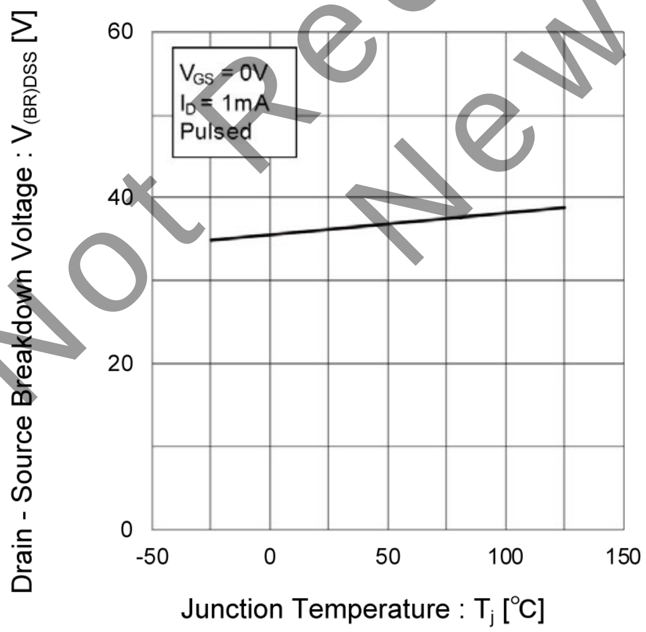
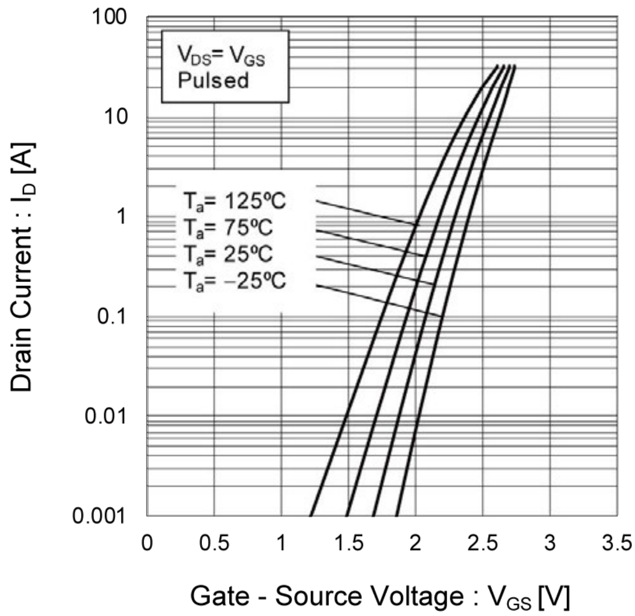



Fig.8 Typical Transfer Characteristics



## ●Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Junction Temperature

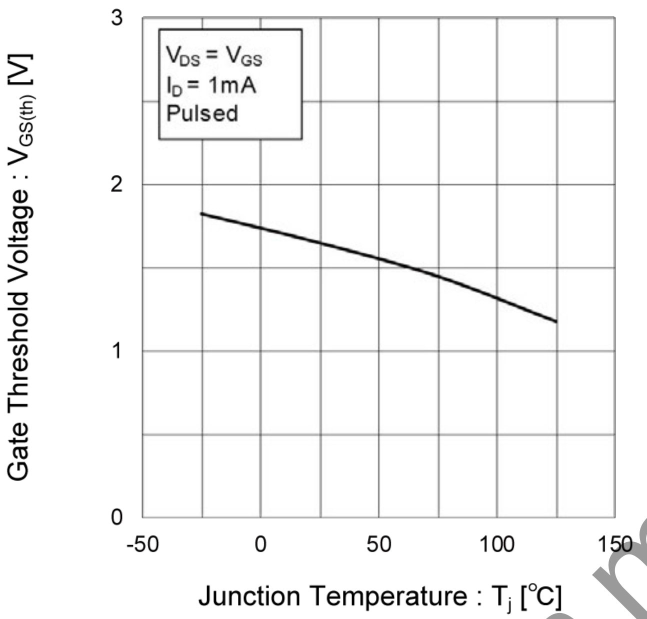



Fig.10 Forward Transfer Admittance vs. Drain Current

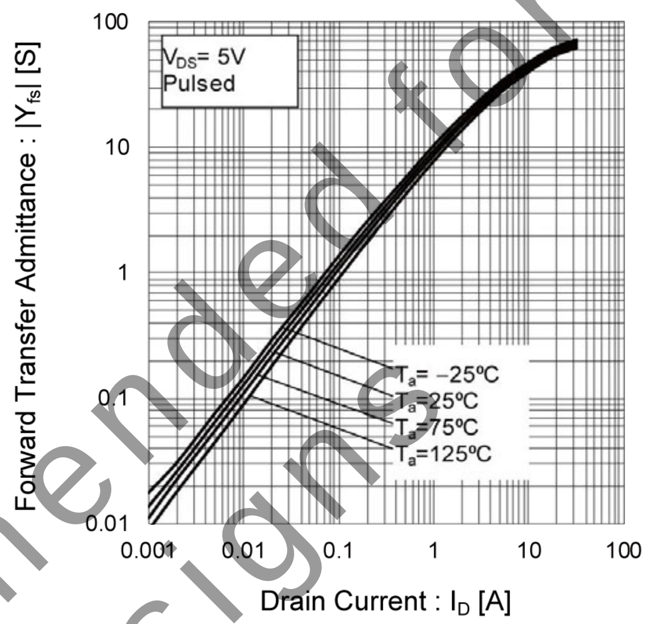



Fig.11 Drain Current Derating Curve

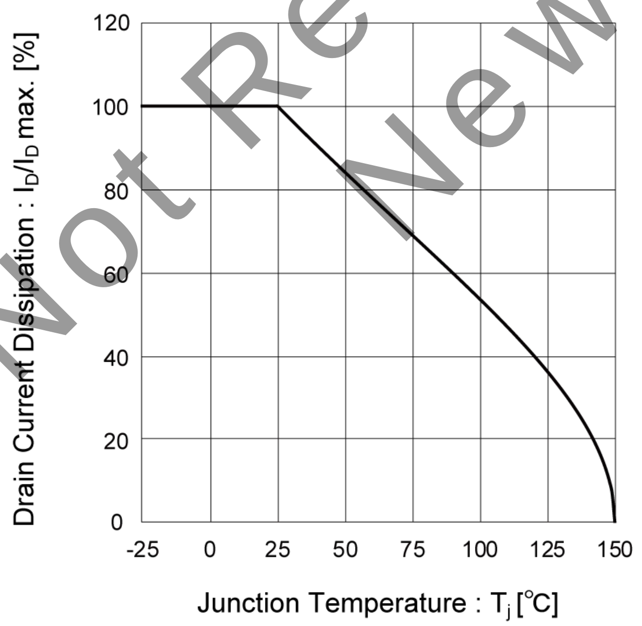
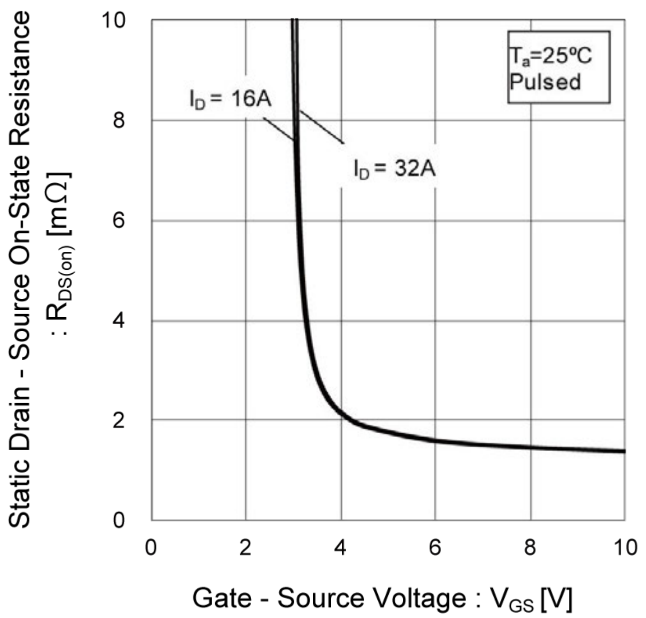



Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



## ●Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

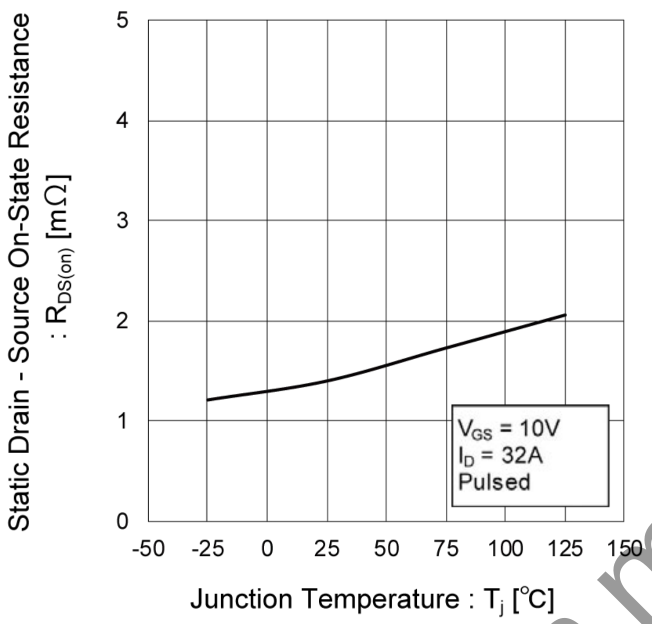



Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

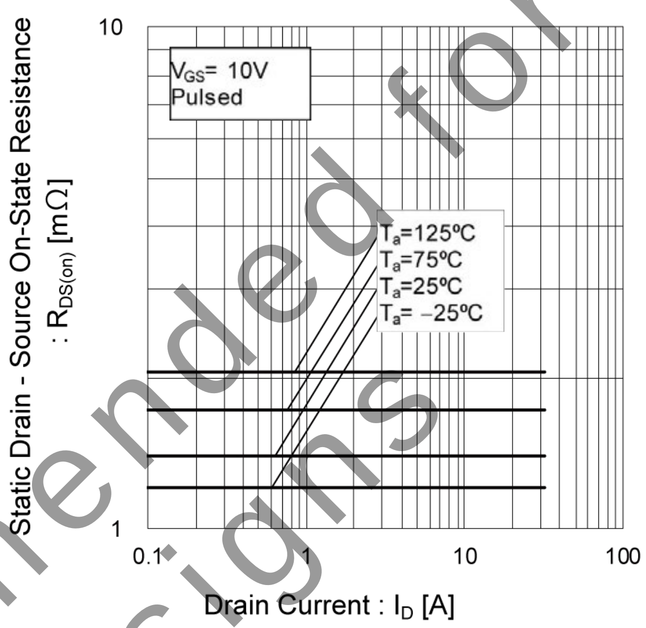
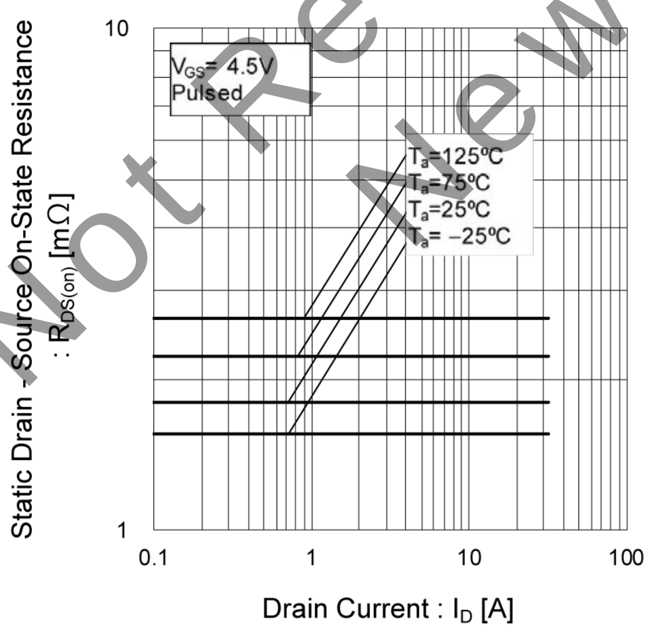



Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)



## ●Electrical characteristic curves

Fig.16 Typical Capacitance vs. Drain - Source Voltage

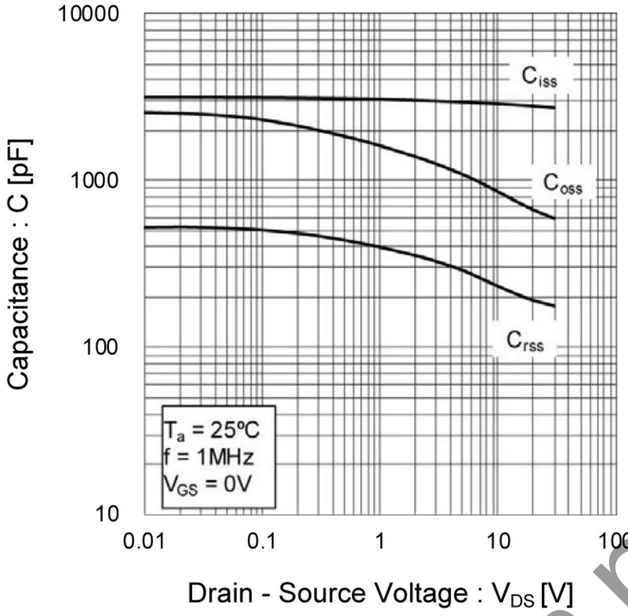



Fig.17 Switching Characteristics

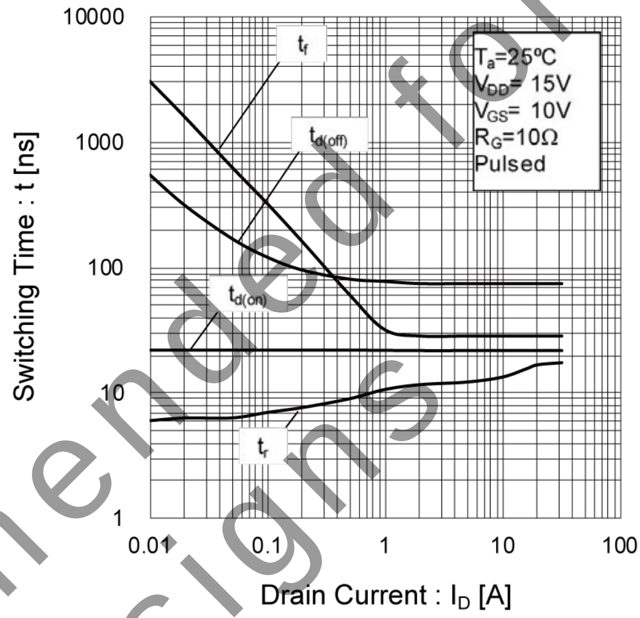



Fig.18 Dynamic Input Characteristics

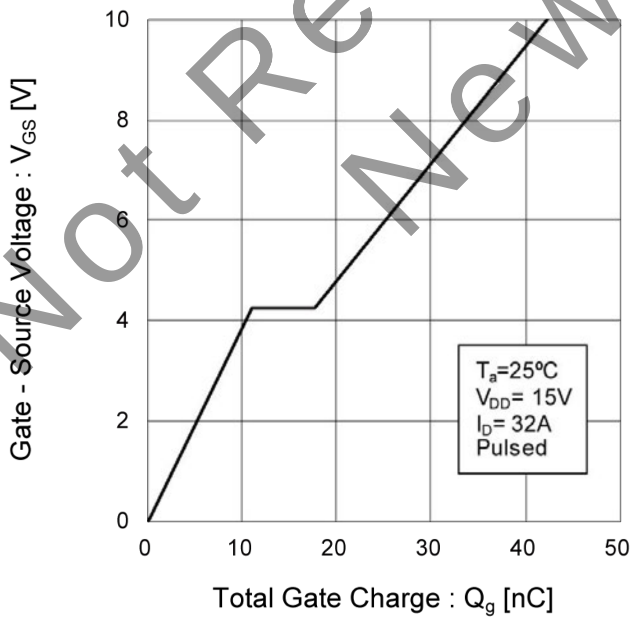
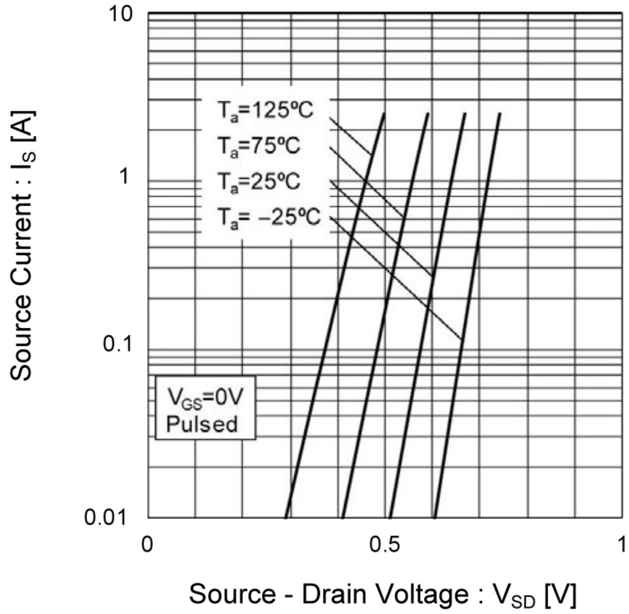



Fig.19 Source Current vs. Source Drain Voltage



## ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

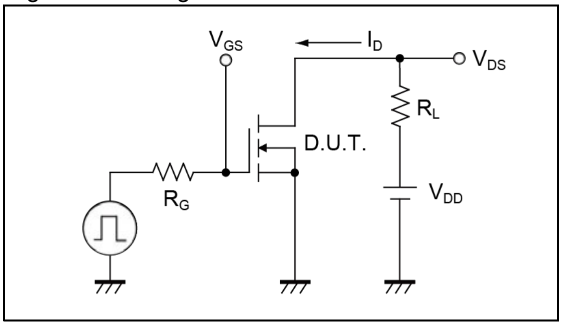



Fig.1-2 Switching Waveforms

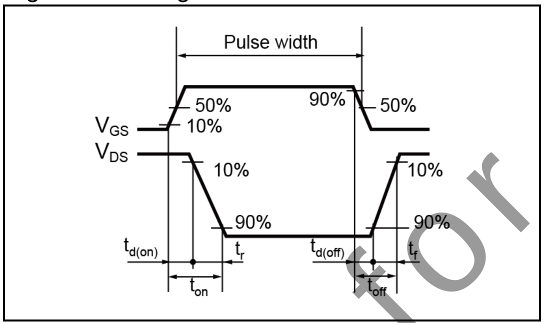



Fig.2-1 Gate Charge Measurement Circuit

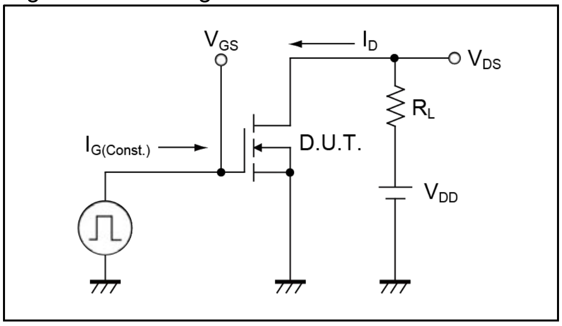



Fig.2-2 Gate Charge Waveform

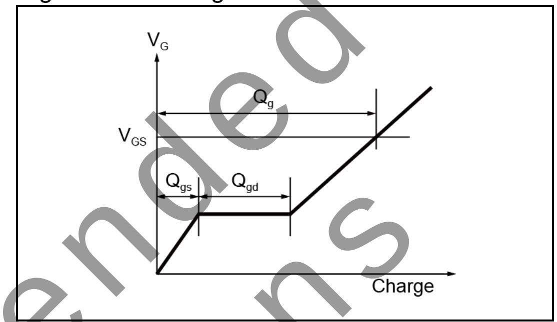



Fig.3-1 Avalanche Measurement Circuit

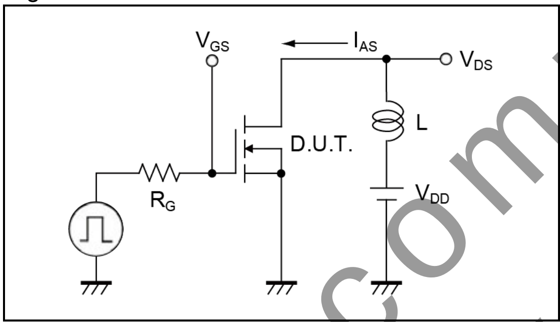
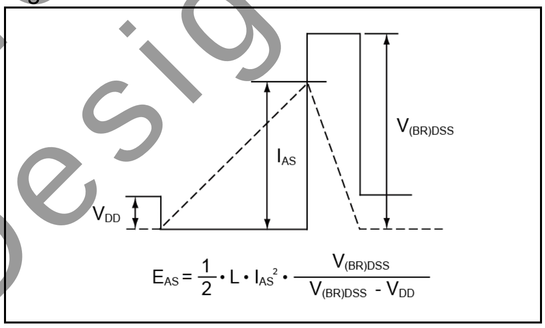



Fig.3-2 Avalanche Waveform

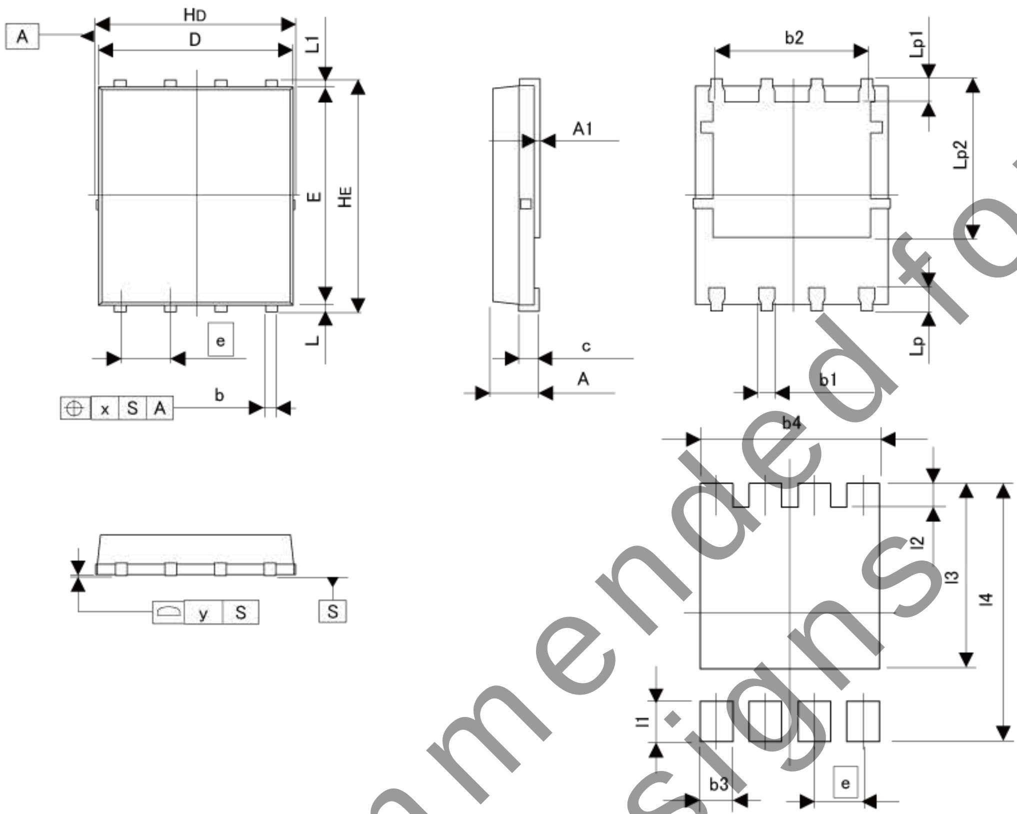



## ●Notice

This product might cause chip aging and breakdown under the large electrified environment.
Please consider to design ESD protection circuit.

## ●Dimensions

HSOP8 ( 5 x 6 )




Pattern of terminal position areas
[Not a pattern of soldering pads]

| DIM | MILIMETERS | | INCHES | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| A | 0.90 | 1.10 | 0.035 | 0.043 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| b | 0.24 | 0.42 | 0.009 | 0.017 |
| b1 | 0.29 | 0.49 | 0.011 | 0.019 |
| b2 | 3.81 | 4.21 | 0.150 | 0.166 |
| c | 0.20 | 0.30 | 0.008 | 0.012 |
| D | 4.80 | 5.00 | 0.189 | 0.197 |
| E | 5.60 | 5.80 | 0.220 | 0.228 |
| e | 1.27 | | 0.050 | |
| HD | 4.90 | 5.10 | 0.193 | 0.201 |
| HE | 5.90 | 6.10 | 0.232 | 0.240 |
| L | 0.07 | 0.25 | 0.003 | 0.010 |
| L1 | 0.07 | 0.25 | 0.003 | 0.010 |
| Lp | 0.50 | 0.70 | 0.020 | 0.028 |
| Lp1 | 0.52 | 0.72 | 0.020 | 0.028 |
| Lp2 | 3.92 | 4.32 | 0.154 | 0.170 |
| x | - | 0.10 | - | 0.004 |
| y | - | 0.10 | - | 0.004 |

| DIM | MILIMETERS | | INCHES | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| b3 | - | 0.59 | - | 0.023 |
| b4 | - | 4.21 | - | 0.166 |
| l1 | - | 0.80 | - | 0.031 |
| l2 | - | 0.82 | - | 0.032 |
| l3 | - | 4.32 | - | 0.170 |
| l4 | - | 6.10 | - | 0.240 |

Dimension in mm/inches

# Notice

## Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

| JAPAN | USA | EU | CHINA |
|---|---|---|---|
| CLASSⅢ | CLASSⅢ | CLASSⅡb | CLASSⅢ |
| CLASSⅣ | | CLASSⅢ | |

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

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   [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including $Cl_2$, $H_2S$, $NH_3$, $SO_2$, and $NO_2$
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

**Precautions Regarding Application Examples and External Circuits**

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

**Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

**Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

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